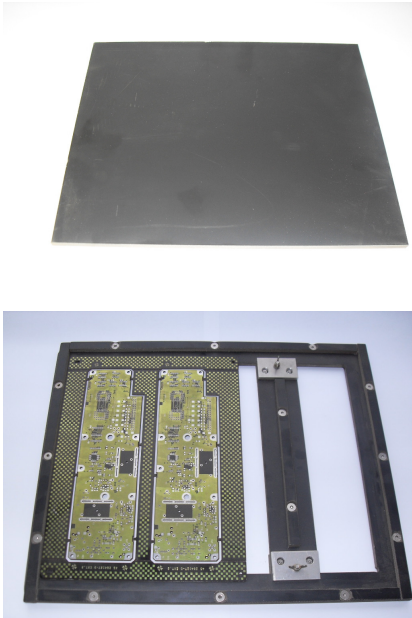


## Multitemp H2000



Properties	Units	Typical Value
Water absorption	%	0.15 – 0.2 %
Operating Temperature, Continuous	°C	300
Operating Temperature, Short-term	°C	350
Coeff. Of linear thermal expansion	10 <sup>-6</sup> x K-1	11.7, 1-20
Thermal Conductivity	W/mK	0.30
Compressive strength at 23 °C	N/mm <sup>2</sup>	600
Compressive strength at 200 °C	N/mm <sup>2</sup>	350
Flexural strength	N/mm <sup>2</sup> - MPa	300
Flexural Modulus	N/mm <sup>2</sup> - MPa	16000
Surface Resistivity	Ω <sup>2</sup>	10 <sup>12</sup>

### Product description:

Multitemp H2000 has been developed specifically for the manufacture of solder pallets. The surface operating temperature of 300 °C makes the product ideally suited for infra red/convection re-flow, and wave solder applications.

Multitemp H2000 is suited to applications where Electro-Static Dissipation (ESD) is a consideration.

### Availability:

Multitemp H2000 can be delivered as sheet cut-offs and finished parts.

- Max. sheet dimension 1000 x 2000 mm
- Thickness 4, 6, 8 & 10 mm